



General Description

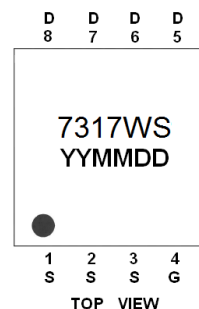
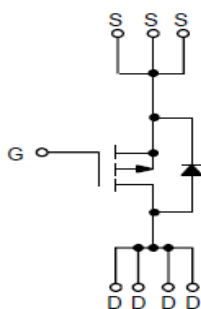
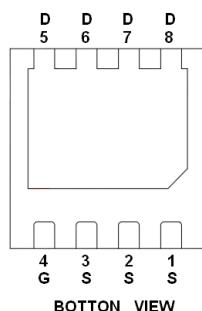
AFP7317WS, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- $I_D = -1.4A, R_{DS(ON)} = 750\text{ m}\Omega @ V_{GS} = -10V$
- $I_D = -1.0A, R_{DS(ON)} = 800\text{ m}\Omega @ V_{GS} = -6V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN3X3-8L package design

Pin Description (DFN3X3-8L)



Application

- DC-DC Converter
- POL

Pin Define

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP7317WSFN338RG	7317WS	DFN3X3-8L	Tape & Reel	5000 EA

- ※ YY year code
- ※ MM month code
- ※ DD date code

※ AFP7317WSFN338RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



※ **Absolute Maximum Ratings** ($T_A=25^\circ\text{C}$ Unless otherwise noted)

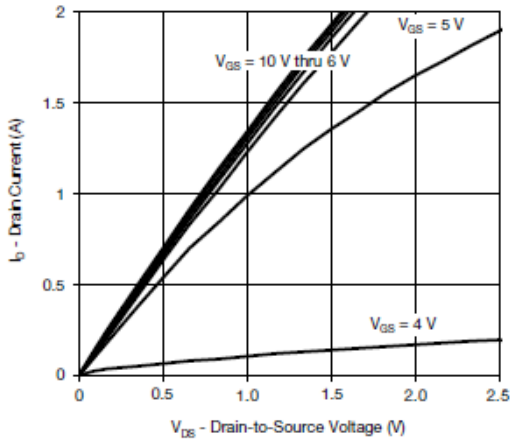
Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V_{DS}	-150	V	
Gate -Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current ($T_J=150^\circ\text{C}$)	I_D	$T_C=25^\circ\text{C}$ $T_A=25^\circ\text{C}$	-3.0	A
		$T_C=70^\circ\text{C}$ $T_A=70^\circ\text{C}$	-2.4 -1.0	
Pulsed Drain Current	I_{DM}	-3.2	A	
Single pulse avalanche energy	E_{AS}	0.5	mJ	
Continuous Source Current (Diode Conduction)	I_S	$T_C=25^\circ\text{C}$ $T_A=25^\circ\text{C}$	-10	A
		$T_C=70^\circ\text{C}$ $T_A=70^\circ\text{C}$	-2.7	
Power Dissipation	P_D	$T_C=25^\circ\text{C}$ $T_A=25^\circ\text{C}$	28	W
		$T_C=70^\circ\text{C}$ $T_A=70^\circ\text{C}$	15 3.2	
Operating Junction Temperature	T_J	150	$^\circ\text{C}$	
Storage Temperature Range	T_{STG}	-55/150	$^\circ\text{C}$	
Thermal Resistance Junction-to-Case (Drain)	$R_{\theta JC}$	5	$^\circ\text{C/W}$	
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	40		

Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless otherwise noted)

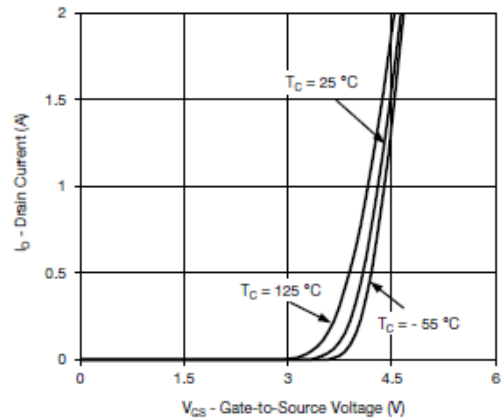
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-150			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-2.0		-4.0	
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-120V, V_{GS}=0V$			-1	uA
		$V_{DS}=-120V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			-30	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq -15V, V_{GS}=-10V$	-1.6			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-1.4A$		685	750	m Ω
		$V_{GS}=-6V, I_D=-1.0A$		735	800	
Forward Transconductance	g_{FS}	$V_{DS}=-15V, I_D=-0.5A$		3		S
Diode Forward Voltage	V_{SD}	$I_S=-1.0A, V_{GS}=0V$		-0.75	-1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=-75V, V_{GS}=-10V$ $I_D \equiv -1.1A$		7.0	12	nC
Gate-Source Charge	Q_{gs}			1.8		
Gate-Drain Charge	Q_{gd}			2.2		
Gate Resistance	R_g	$f=1\text{MHz}$		10	15	Ω
Pulse Diode Forward Current	I_{SM}				-12	A
Input Capacitance	C_{iss}	$V_{DS}=-75V, V_{GS}=0V$ $f=1\text{MHz}$		280		pF
Output Capacitance	C_{oss}			20		
Reverse Transfer Capacitance	C_{rss}			15		
Turn-On Time	$t_{d(on)}$	$V_{DD}=-75V, R_L=85\Omega$ $I_D \equiv -1.0A, V_{GEN}=-10V$ $R_G=1.0\Omega$		10	20	ns
	t_r			15	30	
Turn-Off Time	$t_{d(off)}$			15	30	
	t_f			10	25	
Body Diode Reverse Recovery Time	t_{rr}	$I_F=-0.5A, di/dt=100A/\mu s,$ $T_J=25^\circ\text{C}$		50	100	ns
Body Diode Reverse Recovery Charge	Q_{rr}			95	150	nC



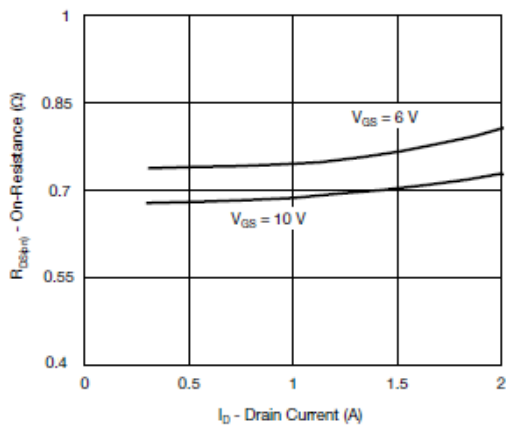
Typical Characteristics



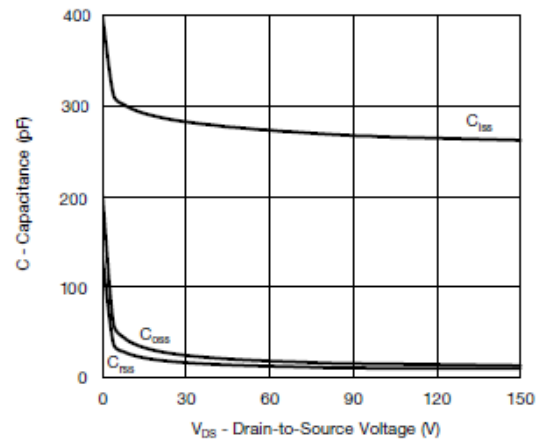
Output Characteristics



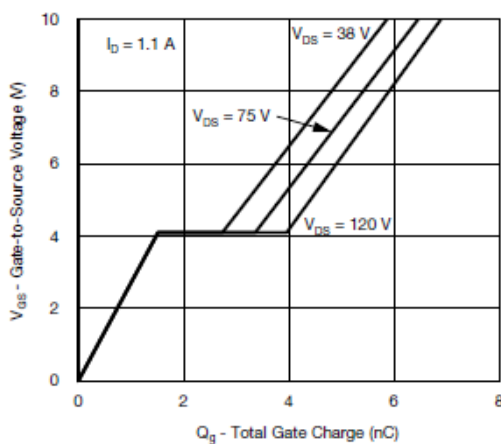
Transfer Characteristics



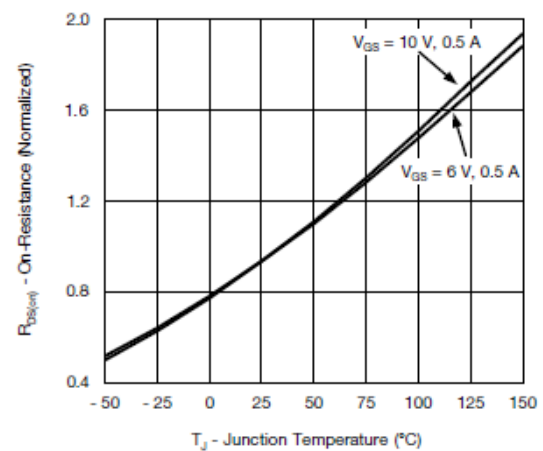
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



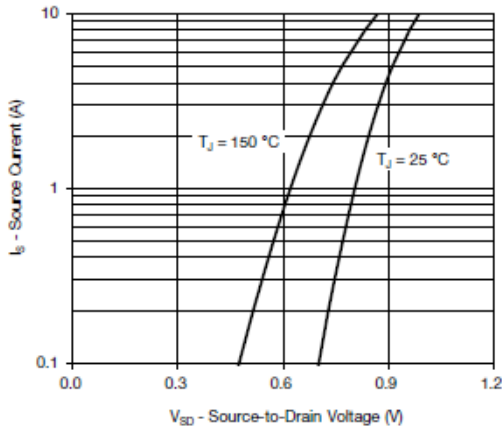
Gate Charge



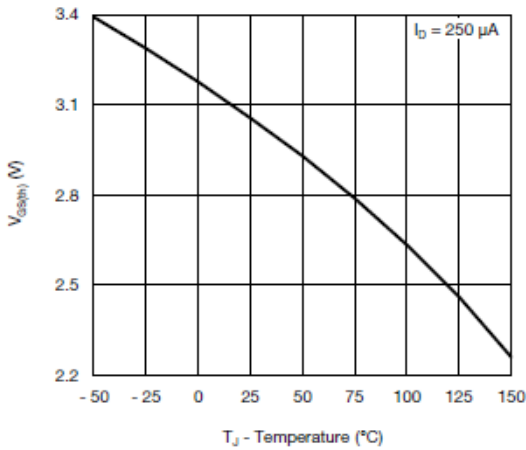
On-Resistance vs. Junction Temperature



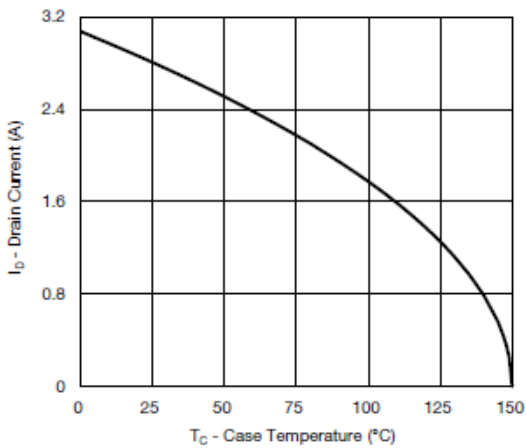
Typical Characteristics



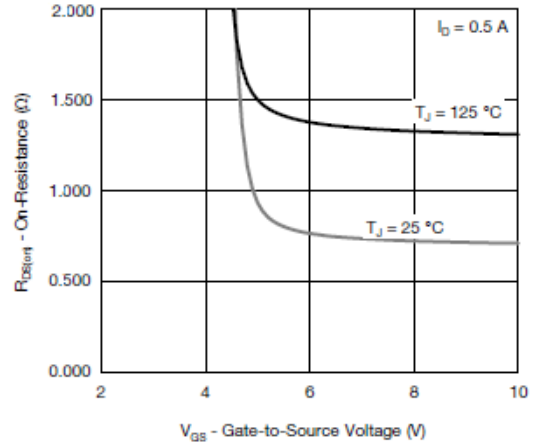
Source-Drain Diode Forward Voltage



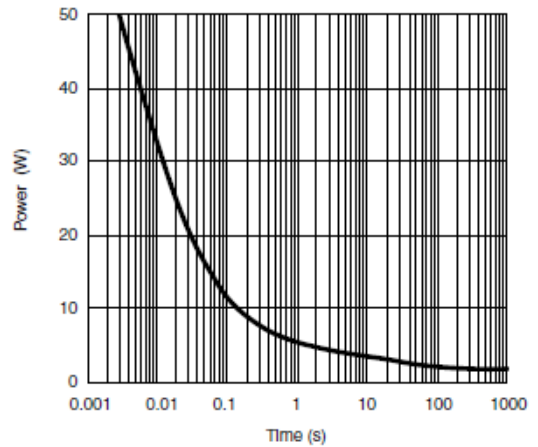
Threshold Voltage



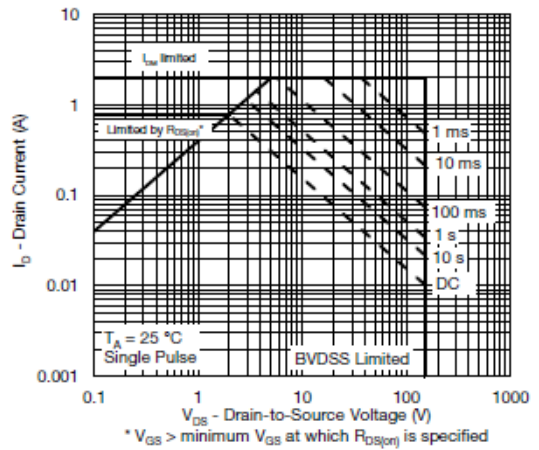
Max Current vs. Case Temperature



On-Resistance vs. Gate-to-Source Voltage



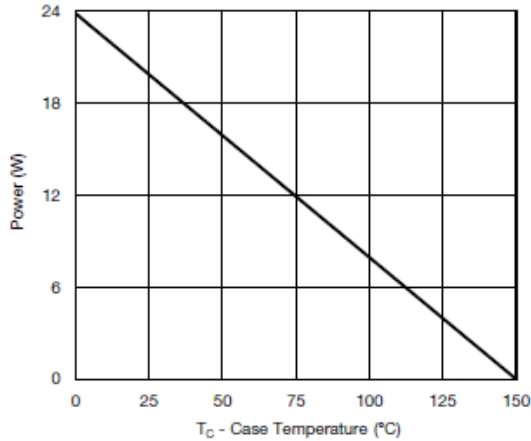
Single Pulse Power, Junction-to-Ambient



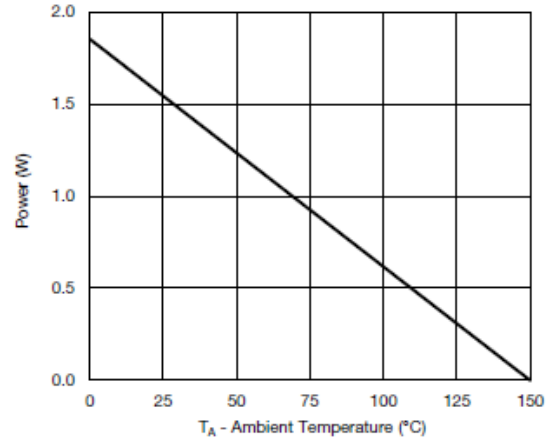
Safe Operating Area at $T_A = 25^\circ\text{C}$



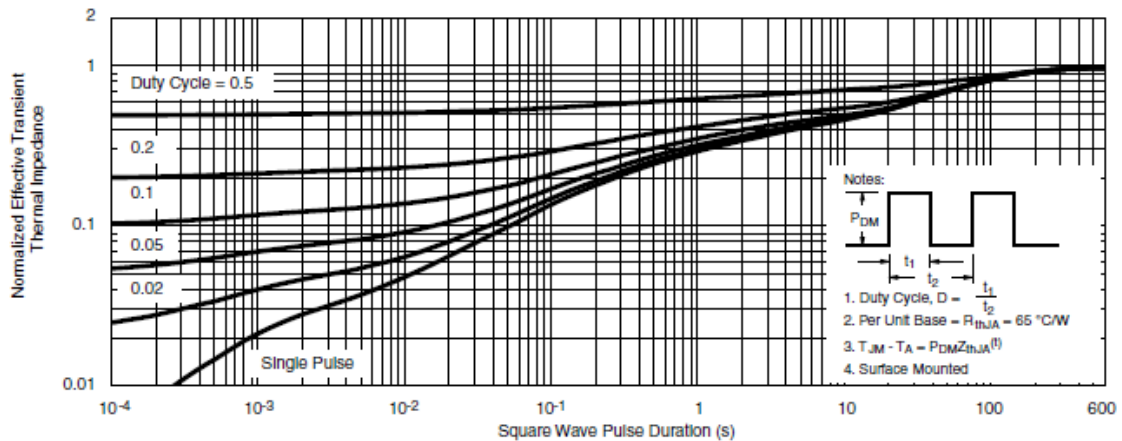
Typical Characteristics



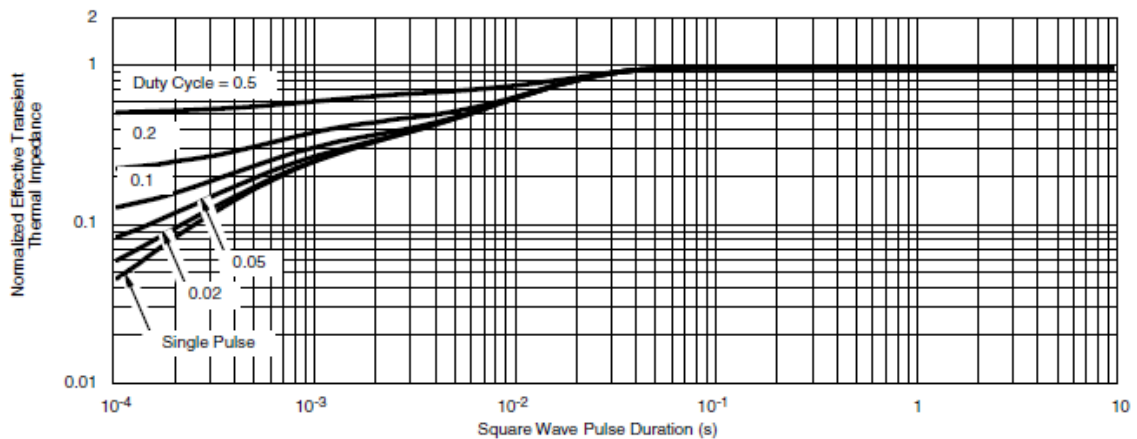
Power Junction-to-Case



Power Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

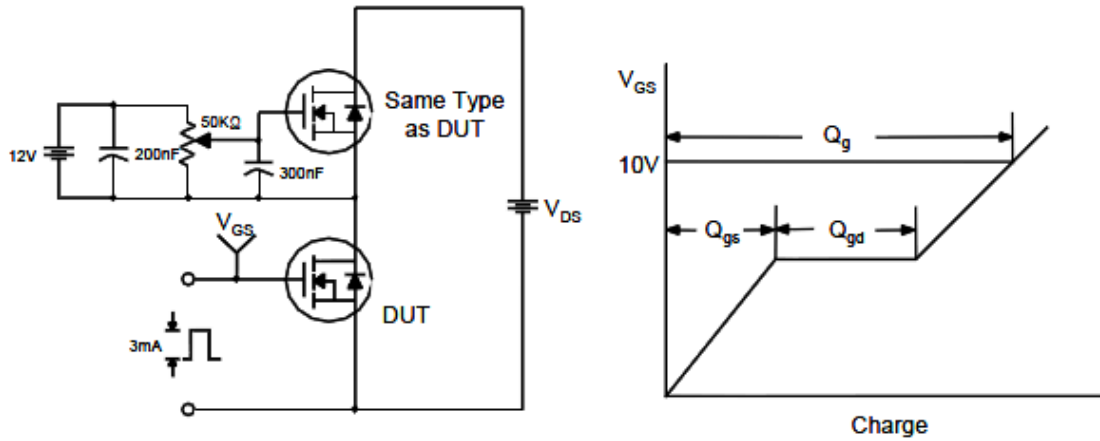


Normalized Thermal Transient Impedance, Junction-to-Case

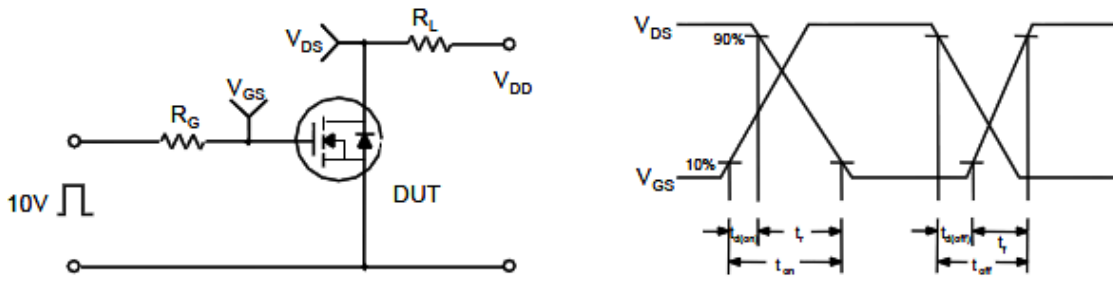


Typical Characteristics

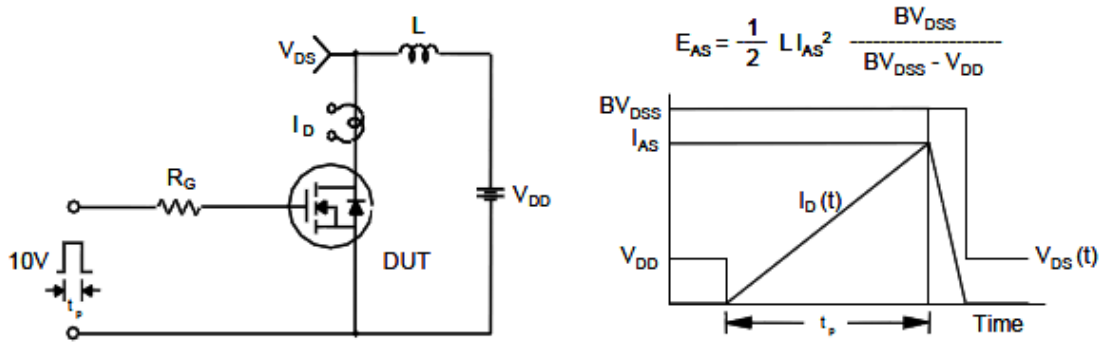
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

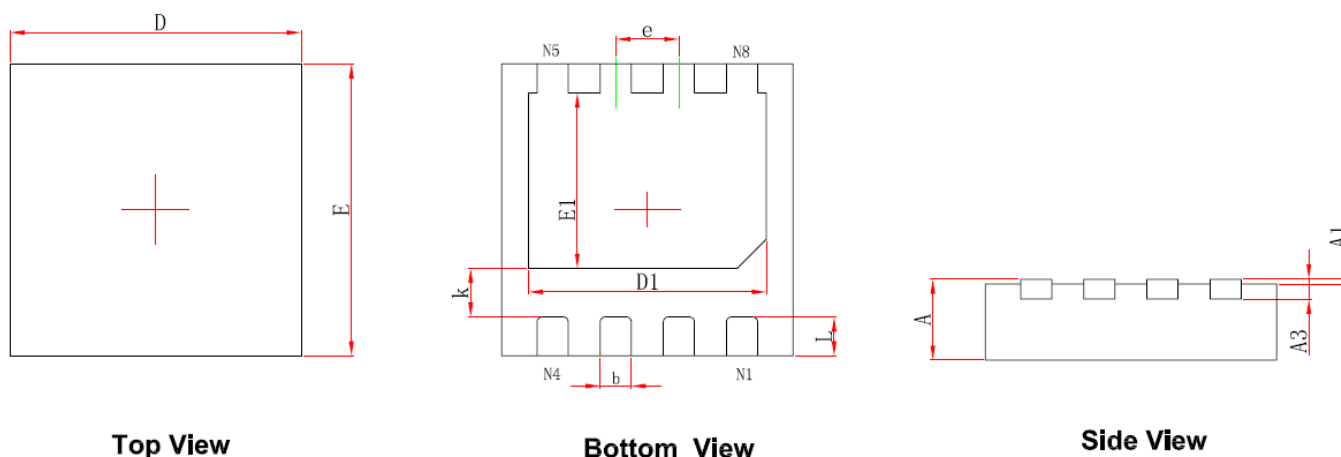


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (DFN3X3-8L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.450	0.550	0.018	0.022
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019

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